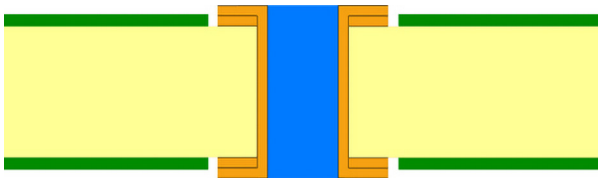


# Via filling

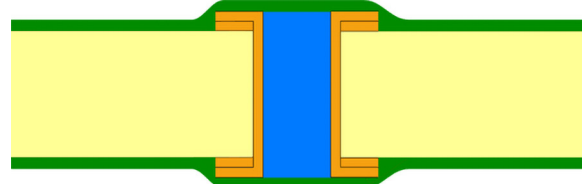
## Non-conductive paste filling

We are using technology from I.T.C. Technology is using the vacuum chamber, so we can make all types of via filling compare to the IPC 4761 and we can fill blind vias too.

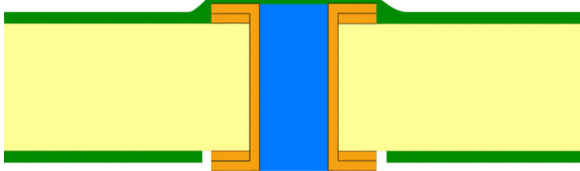
Type V



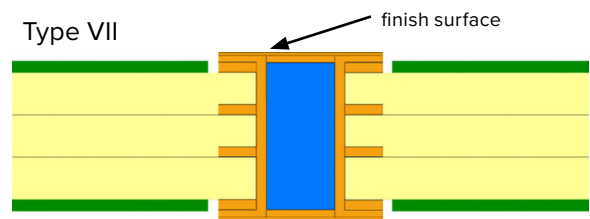
Type VI-b



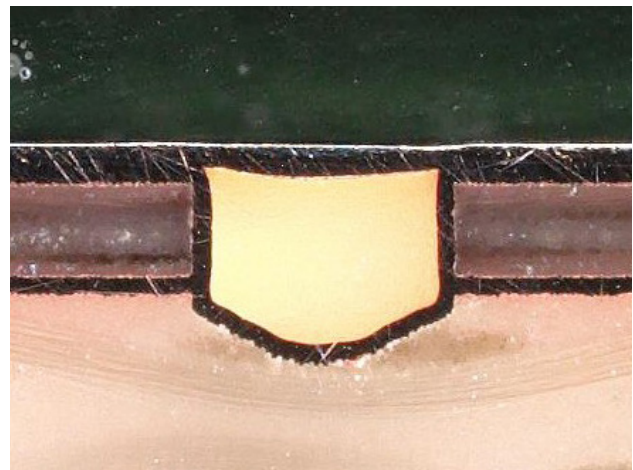
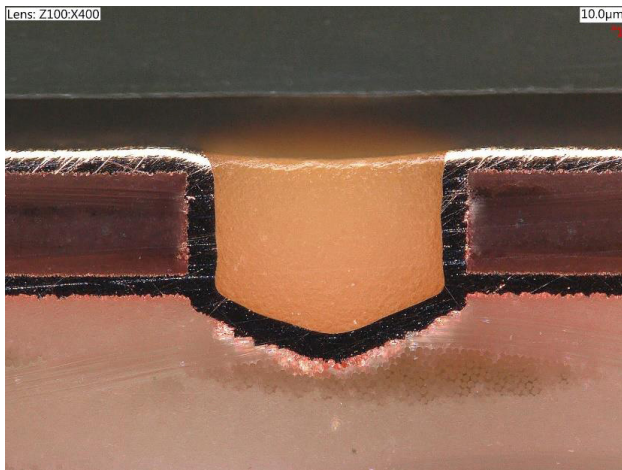
Type VI-a



Type VII



Legend:  laminate       non-conductive paste       soldermask       Cu layer



## Non-conductive paste

Minimal plated hole	0,1 mm
Maximum plated hole	2,0 mm
Aspect ratio for PTH	max. 40:1
Aspect ratio blind hole	max. 1:1
IPC-4761 types	V, VI-a, VI-b, a VII
PCB thickness	0,4–3,2 mm

More about TAYIO paste: <https://www.gatema.com/file-link/filling-paste-tds-thp-100dx1.pdf>